

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-10 (canceled).

Claim 11 (currently amended): A method of manufacturing an electronic component comprising the steps of:

a mounting step including mounting on a collective mounting substrate a plurality of electronic functional elements, each of the plurality of electronic functional elements having a substrate and an electronic functional portion provided on the substrate;

an arranging step including arranging a resin film on the electronic functional elements mounted on the collective mounting substrate;

a reduced-pressure packaging step including putting the electronic functional elements and the resin film mounted on the collective ~~packing-mounting~~ substrate in a bag that has a gas-barrier property, and hermetically sealing the contents inside the bag by closing an opening of the bag after depressurizing the inside of the bag-to ~~hermetically seal the contents inside;~~

a sealing step including sealing the electronic functional elements with a sealing resin member formed from the resin film by causing the resin film to infiltrate between the electronic functional elements mounted on the collective ~~packing-mounting~~ substrate; and

a dividing step including dividing the collective packing ~~substrate-mounting~~ having the resin-sealed electronic functional elements into individual electronic functional elements.

Claim 12 (currently amended): The method of manufacturing an electronic component according to claim 11, wherein the sealing step includes a curing step

causing the resin film to infiltrate between the electronic functional elements, heating the electronic functional elements and the collective mounting substrate covered with a sealing resin precursor formed from the resin film, and curing the sealing resin precursor to obtain the sealing resin member, and the curing step includes performing heating in a pressure-controlled hermetically sealed space.

Claim 13 (currently amended): The method of manufacturing an electronic component according to claim 11, wherein, the electronic functional element is a surface acoustic wave element ~~disposed on a piezoelectric substrate and having a~~ vibration portion as the electronic functional portion disposed on a piezoelectric substrate.

Claim 14 (previously presented): The method of manufacturing an electronic component according to claim 13, wherein, in the mounting step, the vibration portion is arranged so as to have a space between the vibration portion and the collective mounting substrate and so as to face the collective mounting substrate.

Claim 15 (currently amended): The method of manufacturing an electronic component according to claim 14, wherein the resin film includes filler and a maximum particle size of a particle distribution of the filler is larger than a gap between the electronic functional element and the collective mounting substrate, and an amount of the filler having a particle size larger than the gap between the electronic functional element and the ~~packaging collective~~ mounting substrate is about 5 wt % or more with respect to the total amount of filler.

Claim 16 (currently amended): The method of manufacturing an electronic component according to claim 11, wherein, the sealing step further includes heating the resin film to ~~cure-soften~~ the resin film and for applying pressure to the resin film via a roller or a press machine.

Claim 17 (previously presented): The method of manufacturing an electronic component according to claim 11, wherein, the arranging step includes adhering a parting sheet on one surface of the resin film, and arranging the resin film on the collective mounting substrate having the electronic functional elements thereon so that the parting sheet side of the resin film faces outside.

Claim 18 (previously presented): The method of manufacturing an electronic component according to claim 17, wherein, the surface roughness of the resin film side of the parting film is in the range of about 0.01 μm to about 10 μm .

Claim 19 (previously presented): The method of manufacturing an electronic component according to claim 11, wherein, the mounting step includes a flip-chip bonding step for mounting the plurality of electronic functional elements through bumps by flip-chip bonding.

Claim 20 (currently amended): The method of manufacturing an electronic component according to claim 11, wherein, the bag has a multi-layered structure having a thermoplastic resin layer as an innermost layer and a heat-resistant resin layer with a higher heat resistance and gas-barrier property that is higher than those of the ~~thermo-~~thermoplastic resin layer as an outermost layer.